



Material Content Data Sheet



Sales Product Name		BTN8962TA		Issued		3. October 2018		
MA#		MA003664508						
Package		PG-TO263-7-1		Weight*		1534.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	3.697	0.24	0.24	2409	2409
chip_2	inorganic material	silicon	7440-21-3	1.162	0.08	0.08	757	757
chip_3	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	790	790
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
wire	non noble metal	copper	7440-50-8	808.613	52.69	52.76	526871	527557
	non noble metal	aluminium	7429-90-5	5.128	0.33	0.33	3341	3341
encapsulation	organic material	carbon black	1333-86-4	8.821	0.57		5748	
	plastics	epoxy resin	-	97.034	6.32		63225	
leadfinish	inorganic material	silicondioxide	60676-86-0	482.229	31.42	38.31	314207	383180
	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8494	8494
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.124	0.01		81	
	noble metal	silver	7440-22-4	0.155	0.01		101	
heatspreader	non noble metal	lead	7439-92-1	5.921	0.39	0.41	3858	4040
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
*deviation	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69203	69293
	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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